19-2633: Rev 0: 10/02



# **4.5** $\Omega$ Quad SPST Analog Switches in UCSP

#### **General Description**

The MAX4737/MAX4738/MAX4739 low-voltage, low onresistance (RON), quad single-pole/single throw (SPST) analog switches operate from a single +1.8V to +5.5V supply. These devices are designed for USB 1.1 and audio switching applications.

The MAX4737/MAX4738/MAX4739 feature  $4.5\Omega$  R<sub>ON</sub> (max) with 1.2 $\Omega$  flatness and 0.4 $\Omega$  matching between channels. These new switches feature guaranteed operation from +1.8V to +5.5V and are fully specified at 3V and 5V. These switches offer break-before-make switching (1ns) with ton <80ns and toff <40ns at +2.7V. The digital logic inputs are +1.8V logic compatible with a +2.7V to +3.6V supply.

These switches are packaged in a chip-scale package (UCSP™), significantly reducing the required PC board area. The chip occupies only a 2mm x 2mm area and has a  $4 \times 4$  bump array with a bump pitch of 0.5mm. These switches are also available in a 14-pin TSSOP package.

#### **Applications**

**Battery-Operated Equipment** Audio/Video-Signal Routing Low-Voltage Data-Acquisition Systems Sample-and-Hold Circuits Data-Acquisition Systems WWW.DZSC.COM Communications Circuits

UCSP is a trademark of Maxim Integrated Products, Inc. Rail-to-Rail is a registered trademark of Nippon Motorola, Ltd.

# **Features**

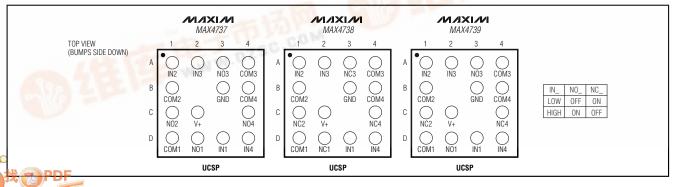
- ♦ USB 1.1 Signal Switching
- 2ns (max) Differential Skew
- -3dB Bandwidth: >300MHz
- Low 20pF On-Channel Capacitance
- **♦ Low Ron** 
  - 4.5 $\Omega$  (max) (+3V Supply)  $3\Omega$  (max) (+5V Supply)
- ♦ 0.4Ω (max) Ron Match (+3V Supply)
- ♦ 1.2Ω (max) Ron Flatness (+3V Supply)
- ♦ <0.5nA Leakage Current at +25°C
  </p>
- ♦ High Off-Isolation: -55dB (10MHz)
- ♦ Low Crosstalk: -80dB (10MHz)
- ♦ Low Distortion: 0.03%
- ♦ +1.8V CMOS-Logic Compatible
- ♦ Single-Supply Operation from +1.8V to +5.5V
- ♦ Rail-to-Rail® Signal Handling

## **Ordering Information**

PART	PART TEMP RANGE		TOP MARK
MAX4737EUD	-40°C to +85°C	14 TSSOP	_
MAX4737EBE-T*	-40°C to +85°C	16 UCSP-16	4737
MAX4738EUD	-40°C to +85°C	14 TSSOP	_
MAX4738EBE-T*	-40°C to +85°C	16 UCSP-16	4738
MAX4739EUD	-40°C to +85°C	14 TSSOP	_
MAX4739EBE-T*	-40°C to +85°C	16 UCSP-16	4739

Note: UCSP package requires special solder temperature profile described in the Absolute Maximum Ratings section.

## Pin Configurations/Functional Diagrams/Truth Tables



Maxim Integrated Products 1

<sup>\*</sup>UCSP reliability is integrally linked to the user's assembly methods, circuit board material, and environment. See the UCSP reliability notice in the UCSP Reliability section of this data sheet for more information.

#### **ABSOLUTE MAXIMUM RATINGS**

(All Voltages Referenced to GND) V+, IN0.3V to +6.	ΟV
COM , NO , NC (Note 1)0.3V to (V+ + 0.3	
Continuous Current COM_, NO_, NC±100n	,
Peak Current COM_, NO_, NC_	
(pulsed at 1ms, 10% duty cycle)±200n	nΑ
Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )	
14-Pin TSSOP (derate 6.3mW/°C above +70°C)500m	١W
16-Bump UCSP (derate 8.3mW/°C above +70°C)659m	١W

>2kV
+85°C
-150°C
-150°C
-300°C
-220°C
-215°C

- **Note 1:** Signals on COM\_, NO\_, or NC\_ exceeding V+ or GND are clamped by internal diodes. Limit forward-diode current to maximum current rating.
- Note 2: This device is constructed using a unique set of packaging techniques that impose a limit on the thermal profile the device can be exposed to during board level solder attach and rework. This limit permits only the use of the solder profiles recommended in the industry standard specification, JEDEC 020A, paragraph 7.6, table 3 for IR/VPR and convection reflow. Preheating is required. Hand or wave soldering is not allowed.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS—Single +3V Supply**

 $(V+=+2.7V \text{ to } +3.6V, V_{IH}=+1.4V, V_{IL}=+0.5V, T_A=T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V+=+3.0V, T_A=+25^{\circ}C, \text{ unless otherwise noted.})$  (Notes 3, 4)

PARAMETER	PARAMETER SYMBOL CONDITIONS		TA	MIN	TYP	MAX	UNITS	
Analog Signal Range	V <sub>COM_</sub> , V <sub>NO_</sub> , V <sub>NC_</sub>			0		V+	V	
ANALOG SWITCH								
		V 0.7V 1 10 A	+25°C		3.0	4.5		
On-Resistance (Note 5)	RON	V+ = 2.7V, I <sub>COM</sub> = 10mA; V <sub>NO</sub> or V <sub>NC</sub> = 1.5V	T <sub>MIN</sub> to T <sub>MAX</sub>			5	Ω	
0. D		V 0.7V 1 10 A	+25°C		0.1	0.4		
On-Resistance Match Between Channels (Notes 5, 6)		$V+ = 2.7V$ , $I_{COM} = 10mA$ ; $V_{NO}$ or $V_{NC} = 1.5V$	T <sub>MIN</sub> to T <sub>MAX</sub>			0.5	Ω	
			+25°C		0.6	1.2		
On-Resistance Flatness (Note 7)	R <sub>FLAT</sub> (ON)	$V_{+} = 2.7V$ , $I_{COM} = 10$ mA; $V_{NO}$ or $V_{NC} = 1.0V$ , 1.5V, 2.0V	T <sub>MIN</sub> to T <sub>MAX</sub>			1.5	Ω	
No No or I i		V+ = 3.6V, V <sub>COM</sub> _ = 0.3V, 3.3V; V <sub>NO</sub> _ or V <sub>NC</sub> _ = 3.3V, 0.3V	+25°C	-0.5	+0.01	+0.5		
NO_, NC_ Off-Leakage Current (Note 8)	INO_(OFF), INC_(OFF)		T <sub>MIN</sub> to T <sub>MAX</sub>	-1		+1	nA	
0014 011 1 0 1		0.01/.1/	+25°C	-0.5	+0.01	+0.5		
COM_ Off-Leakage Current (Note 8)	ICOM_(OFF)	V+ = 3.6V, V <sub>COM</sub> _ = 0.3V, 3.3V; V <sub>NO</sub> _ or V <sub>NC</sub> _ = 3.3V, 0.3V	T <sub>MIN</sub> to T <sub>MAX</sub>	-1		+1	nA	
0014 0 1 1 0		$V + = 3.6V, V_{COM} = 0.3V, 3.3V;$	+25°C	-1	+0.01	+1		
COM_ On-Leakage Current (Note 8)	ICOM_(ON)	$V_{NO}$ or $V_{NC}$ = 0.3V, 3.3V, or floating	T <sub>MIN</sub> to T <sub>MAX</sub>	-2		+2	nA	

### **ELECTRICAL CHARACTERISTICS—Single +3V Supply (continued)**

 $(V+=+2.7V \text{ to } +3.6V, V_{IH}=+1.4V, V_{IL}=+0.5V, T_A=T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.} Typical values are at V+=+3.0V, T_A=+25^{\circ}C, unless otherwise noted.) (Notes 3, 4)$ 

PARAMETER	PARAMETER SYMBOL CONDITIONS					MAX	UNITS	
DYNAMIC CHARACTERISTICS	•		•				•	
			+25°C		40	80		
Turn-On Time	ton	$V_{NO\_}$ , $V_{NC\_}$ = 1.5V; $R_L$ = 300 $\Omega$ , $C_L$ = 35pF, Figure 1	T <sub>MIN</sub> to			100	ns	
		V V 15V	+25°C		20	40		
Turn-Off Time	t <sub>OFF</sub>	$V_{NO\_}$ , $V_{NC\_}$ = 1.5V; $R_L$ = 300 $\Omega$ , $C_L$ = 35pF, Figure 1	T <sub>MIN</sub> to			50	ns	
B 1 B ( M 1 T B 1		V V 15V	+25°C		8			
Break-Before-Make Time Delay (MAX4739 Only) (Note 8)	t <sub>BBM</sub>	$V_{NO}$ , $V_{NC}$ = 1.5V; $R_L$ = 300 $\Omega$ , $C_L$ = 35pF, Figure 2	T <sub>MIN</sub> to	1			ns	
Skew (Note 8)	tskew	$R_S = 39\Omega$ , $C_L = 50pF$ , Figure 3	T <sub>MIN</sub> to T <sub>MAX</sub>		0.15	2	ns	
Charge Injection	Q	$V_{GEN} = 2V$ , $R_{GEN} = 0\Omega$ , $C_L = 1.0$ nF, Figure 4	+25°C		5		рС	
Off Indiation (Nata 0)	V	$f = 10MHz$ ; $V_{NO}$ , $V_{NC}$ = $1V_{P-P}$ ; $R_L = 50\Omega$ , $C_L = 5pF$ , Figure 5a	0500		-55		dB	
Off-Isolation (Note 9)	V <sub>ISO</sub>	$f = 1MHz; V_{NO\_}, V_{NC\_} = 1V_{P-P};$ $R_L = 50\Omega, C_L = 5pF, Figure 5a$	+25°C		-80		ub	
Occasion (Nicha 40)	V.	$f = 10MHz; V_{NO\_}, V_{NC\_} = 1V_{P-P};$ $R_L = 50\Omega, C_L = 5pF, Figure 5b$	0500	-80			-ID	
Crosstalk (Note 10)	VcT	$f = 1MHz; V_{NO}, V_{NC} = 1V_{P-P};$ $R_L = 50\Omega, C_L = 5pF, Figure 5b$	+25°C		-110		dB	
On-Channel -3dB Bandwidth	BW	Signal = 0dBm, $C_L$ = 5pF, $50\Omega$ in and out, Figure 5a	+25°C		300		MHz	
Total Harmonic Distortion	THD	$R_L = 600\Omega$	+25°C		0.03		%	
NO_, NC_ Off-Capacitance CNO_(OFF) CNC_(OFF)		f = 1MHz, Figure 6	+25°C		9		pF	
Switch On-Capacitance	Con	f = 1MHz, Figure 6	+25°C		15		рF	
DIGITAL I/O								
Input Logic High Voltage	VIH		T <sub>MIN</sub> to T <sub>MAX</sub>	1.4			V	
Input Logic Low Voltage	Logic Low Voltage V <sub>IL</sub> T <sub>MIN</sub> to T <sub>MAX</sub>			0.5	V			
Input Leakage Current	I <sub>IN</sub>	V+ = 3.6V, V <sub>IN</sub> _ = 0 or 5.5V	T <sub>MIN</sub> to T <sub>MAX</sub>	-0.1		+0.1	μΑ	

#### **ELECTRICAL CHARACTERISTICS—Single +3V Supply (continued)**

 $(V+=+2.7V \text{ to } +3.6V, V_{IH}=+1.4V, V_{IL}=+0.5V, T_A=T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V+=+3.0V, T_A=+25^{\circ}C, \text{ unless otherwise noted.)}$  (Notes 3, 4)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN	TYP	MAX	UNITS
SUPPLY							
Supply Voltage Range	V+		T <sub>MIN</sub> to T <sub>MAX</sub>	1.8		5.5	V
Positive Supply Current	l+	V+ = 5.5V, V <sub>IN</sub> _ = 0V or V+	T <sub>MIN</sub> to T <sub>MAX</sub>			1	μΑ

### **ELECTRICAL CHARACTERISTICS—Single +5V Supply**

 $(V+=+4.2V \text{ to } +5.5V, V_{IH}=+2.0V, V_{IL}=+0.8V, T_A=T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V+=+5.0V, T_A=+25^{\circ}C, \text{ unless otherwise noted.})$  (Notes 3, 4)

PARAMETER	SYMBOL	CONDITIONS	TA	MIN	TYP	MAX	UNITS	
Analog Signal Range	V <sub>COM_</sub> , V <sub>NO_</sub> , V <sub>NC_</sub>		T <sub>MIN</sub> to T <sub>MAX</sub>	0		V+	V	
ANALOG SWITCH								
		\\\\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	+25°C		1.7	3.0		
On-Resistance (Note 5)	RON	V+ = 4.2V; I <sub>COM</sub> = 10mA; V <sub>NO</sub> or V <sub>NC</sub> = 3.5V	T <sub>MIN</sub> to T <sub>MAX</sub>			35	Ω	
On Desistance Matela Detuna		10.0	+25°C		0.1	0.3		
On-Resistance Match Between Channels (Notes 5, 6)	ΔR <sub>ON</sub>	V+ = 4.2V; I <sub>COM</sub> = 10mA; V <sub>NO</sub> or V <sub>NC</sub> = 3.5V	T <sub>MIN</sub> to T <sub>MAX</sub>			0.4	Ω	
		10 d 0 d 0 d 0 d 0 d 0 d 0 d 0 d 0 d 0 d	+25°C		0.4	1.2		
On-Resistance Flatness (Note 7)	R <sub>FLAT</sub> (ON)	V+ = 4.2V; I <sub>COM</sub> _ = 10mA; V <sub>NO</sub> _ or V <sub>NC</sub> _ = 1.0V, 2.0V, 3.5V	T <sub>MIN</sub> to			1.5	Ω	
NO NO OWA	INO_(OFF), INC_(OFF)	V+ = 5.5V; V <sub>COM</sub> _ = 1.0V, 4.5V; V <sub>NO</sub> _ or V <sub>NC</sub> _ = 4.5V, 1.0V	+25°C	-0.5	0.01	+0.5	nA	
NO_, NC_ Off-Leakage Current (Note 8)			T <sub>MIN</sub> to	-1		+1		
0011 011 1 0	ICOM_(OFF)		+25°C	-0.5	0.01	+0.5		
COM_ Off-Leakage Current (Note 8)		V+ = 5.5V; V <sub>COM</sub> = 1V, 4.5V; V <sub>NO</sub> or V <sub>NC</sub> = 4.5V, 1V	T <sub>MIN</sub> to	-1		+1	nA	
COM On London Comment		V+ = 5.5V; V <sub>COM</sub> = 1.0V, 4.5V;	+25°C	-1	0.01	+1		
COM_ On-Leakage Current (Note 8)	ICOM_(ON)	$V_{NO}$ or $V_{NC}$ = 1.0V, 4.5V, or floating	T <sub>MIN</sub> to	-2		+2	nA	
DYNAMIC CHARACTERISTICS								
			+25°C		30	80		
Turn-On Time	t <sub>ON</sub>	$V_{NO}$ , $V_{NC}$ = 3.0V; $R_L$ = 300 $\Omega$ , $C_L$ = 35pF, Figure 1	T <sub>MIN</sub> to			100	ns	
			+25°C	+25°C 20	20	40		
Turn-Off Time	toff	$V_{NO\_}$ , $V_{NC\_}$ = 3.0V; $R_L$ = 300 $\Omega$ , $C_L$ = 35pF, Figure 1	T <sub>MIN</sub> to			50	ns	

#### **ELECTRICAL CHARACTERISTICS—Single +5V Supply (continued)**

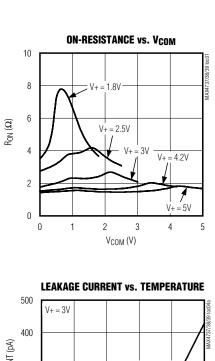
(V+ = +4.2V to +5.5V,  $V_{IH}$  = +2.0V,  $V_{IL}$  = +0.8V,  $T_A$  =  $T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at V+ = +5.0V,  $T_A$  = +25°C, unless otherwise noted.) (Notes 3, 4)

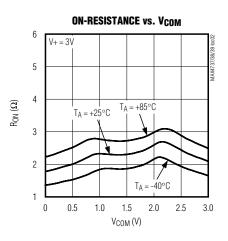
PARAMETER	SYMBOL	CONDITIONS	TA	MIN	TYP	MAX	UNITS
Brook Before Make Time Delay		V V 2 0V	+25°C		8		
Break-Before-Make Time Delay (MAX4739 Only) (Note 8)	tBBM	$V_{NO\_}$ , $V_{NC\_}$ = 3.0V; $R_L$ = 300 $\Omega$ , $C_L$ = 35pF, Figure 2	T <sub>MIN</sub> to	1			ns
Skew (Note 8)	tskew	$R_S = 39\Omega$ , $C_L = 50pF$ , Figure 3	T <sub>MIN</sub> to		0.15	2	ns
DIGITAL I/O							
Input Logic High Voltage	VIH		T <sub>MIN</sub> to T <sub>MAX</sub>	2.0			V
Input Logic Low Voltage	VIL		T <sub>MIN</sub> to			0.8	V
Input Leakage Current	I <sub>IN</sub>	V+ = 5.5V, V <sub>IN</sub> _ = 0V or V+	T <sub>MIN</sub> to	-0.1		+0.1	μΑ
POWER SUPPLY							
Power-Supply Range	V+		T <sub>MIN</sub> to	1.8		5.5	V
Positive Supply Current	l+	V+ = 5.5V, V <sub>IN</sub> _ = 0V or V+	T <sub>MIN</sub> to			1	μA

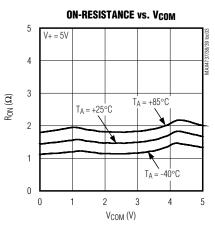
- **Note 3:** UCSP parts are 100% tested at +25°C only, and guaranteed by design over the specified temperature range. TSSOP parts are 100% tested at T<sub>MAX</sub> and guaranteed by design over the specified temperature range.
- **Note 4:** The algebraic convention used in this data sheet is where the most negative value is a minimum and the most positive value is a maximum.
- Note 5: Guaranteed by design for UCSP parts.
- **Note 6:**  $\Delta R_{ON} = R_{ON(MAX)} R_{ON(MIN)}$ .
- **Note 7:** Flatness is defined as the difference between the maximum and minimum value of on-resistance as measured over the specified analog signal ranges.
- Note 8: Guaranteed by design.
- Note 9: Off-Isolation = 20log<sub>10</sub> (V<sub>COM</sub> / V<sub>NO</sub>), V<sub>COM</sub> = output, V<sub>NO</sub> = input to off switch.
- Note 10: Between any two switches.

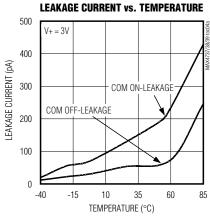
### **Typical Operating Characteristics**

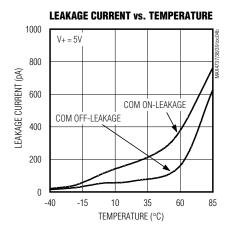
 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 

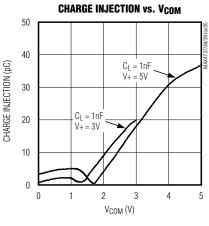


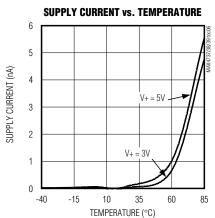


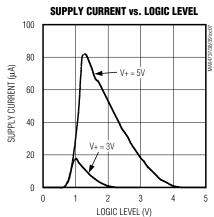


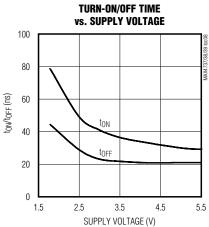






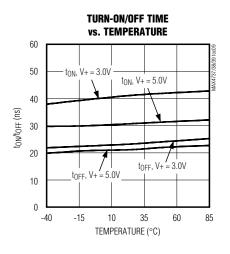


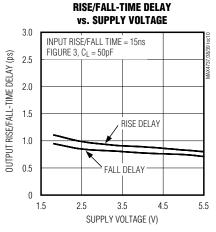


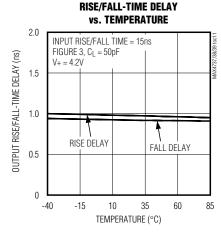


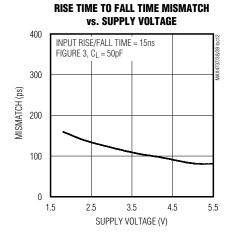
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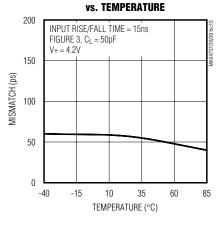
 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 



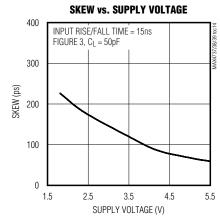


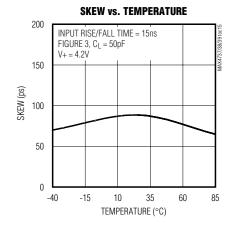


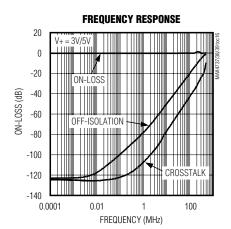




RISE TIME TO FALL TIME MISMATCH

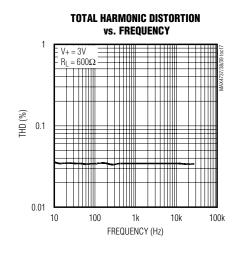


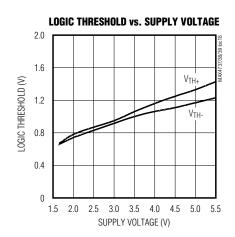




### Typical Operating Characteristics (continued)

 $(T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 





## **Pin Description**

		P	IN				
MAX	4737	MAX	4738	MAX	(4739	NAME	FUNCTION
UCSP	TSSOP	UCSP	TSSOP	UCSP	TSSOP		
D2	1	_	_	D2	1	NO1	Analog-Switch Normally Open Terminal
_	_	D2	1	_	_	NC1	Analog-Switch Normally Closed Terminal
D1	2	D1	2	D1	2	COM1	Analog-Switch Common Terminal
C1	3	_	_	_	_	NO2	Analog-Switch Normally Open Terminal
_	_	C1	3	C1	3	NC2	Analog-Switch Normally Closed Terminal
B1	4	B1	4	B1	4	COM2	Analog-Switch Common Terminal
A1	5	A1	5	A1	5	IN2	Logic-Control Digital Input
A2	6	A2	6	A2	6	IN3	Logic-Control Digital Input
В3	7	В3	7	В3	7	GND	Ground. Connect to digital ground.
А3	8	_	_	АЗ	8	NO3	Analog-Switch Normally Open Terminal
_	_	АЗ	8	_	_	NC3	Analog-Switch Normally Closed Terminal
A4	9	A4	9	A4	9	COM3	Analog-Switch Common Terminal
B4	10	B4	10	B4	10	COM4	Analog-Switch Common Terminal
C4	11	_	_	_	_	NO4	Analog-Switch Normally Open Terminal
_	_	C4	11	C4	11	NC4	Analog-Switch Normally Closed Terminal
D4	12	D4	12	D4	12	IN4	Logic-Control Digital Input
D3	13	D3	11	D3	11	IN1	Logic-Control Digital Input
C2	14	C2	14	C2	14	V+	Positive Analog Supply

#### **Detailed Description**

The MAX4737/MAX4738/MAX4739 quad SPST analog switches operate from a single +1.8V to +5.5V supply. The MAX4737/MAX4738/MAX4739 offer excellent AC characteristics, <0.5nA leakage current, less than 1ns differential skew, and 15pF on-channel capacitance. All of these devices are CMOS-logic compatible with V+ to GND signal handling capability.

The MAX4737/MAX4738/MAX4739 are USB-complaint switches that provide  $4.5\Omega$  (max) on-resistance and 15pF on-channel capacitance to maintain signal integrity. At 12Mbps (USB full-speed data rate specification), the MAX4737/MAX4738/MAX4739 introduce less than 2ns propagation delay between input and output signals and less than 0.5ns change in skew for the output signals (see Figure 4).

The MAX4737 has four normally open (NO) switches, the MAX4738 has four normally closed (NC) switches, and the MAX4739 has two NO switches and two NC switches.

## Applications Information

#### **Digital Control Inputs**

The MAX4737/MAX4738/MAX4739 logic inputs accept up to +5.5V regardless of supply voltage. For example, with a +3.3V supply, IN\_ can be driven low to GND and high to +5.5V allowing for mixing of logic levels in a system. Driving the control logic inputs rail-to-rail minimizes power consumption. For a +1.8V supply voltage, the logic thresholds are 0.5V (low) and 1.4V (high); for a +5V supply voltage, the logic thresholds are 0.8V (low) and 2.0V (high).

#### **Analog Signal Levels**

Analog signals that range over the entire supply voltage (V+ to GND) are passed with very little change in on-resistance (see *Typical Operating Characteristics*). The switches are bidirectional, so the NO\_, NC\_, and COM\_ pins can be either inputs or outputs.

#### **Power-Supply Bypassing**

Power-supply bypassing improves noise margin and prevents switching noise from propagating from the V+ supply to other components. A  $0.1\mu F$  capacitor connected from V+ to GND is adequate for most applications.

#### **UCSP Package Considerations**

For general UCSP package information and PC layout considerations, please refer to the Maxim Application Note (Wafer-Level Chip-Scale Package).

#### **UCSP Reliability**

The chip-scale package (UCSP) represents a unique packaging form factor that may not perform equally to a packaged product through traditional mechanical reliability tests. UCSP reliability is integrally linked to the user's assembly methods, circuit board material, and usage environment. The user should closely review these areas when considering use of a UCSP package. Performance through Operating Life Test and Moisture Resistance remains uncompromised as it is primarily determined by the wafer-fabrication process.

Mechanical stress performance is a greater consideration for a UCSP package. UCSPs are attached through direct solder contact to the user's PC board, foregoing the inherent stress relief of a packaged product lead frame. Solder joint contact integrity must be considered. Information on Maxim's qualification plan, test data, and recommendations are detailed in the UCSP application note, which can be found on Maxim's website at www.maxim-ic.com.

#### **Test Circuits/Timing Diagrams**

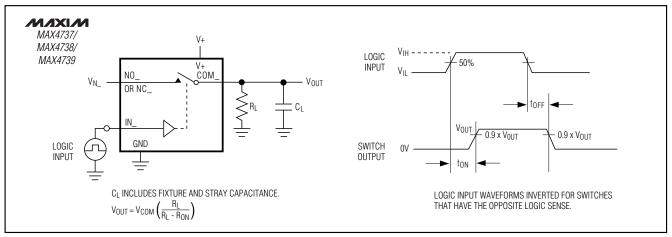


Figure 1. Switching Time

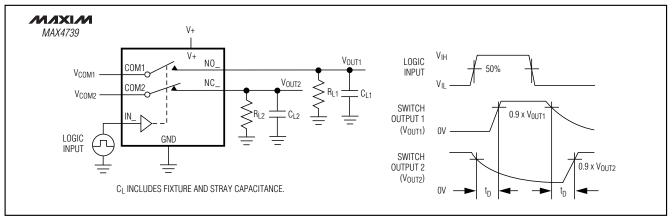


Figure 2. Break-Before-Make Interval

## Test Circuits/Timing Diagrams (continued)

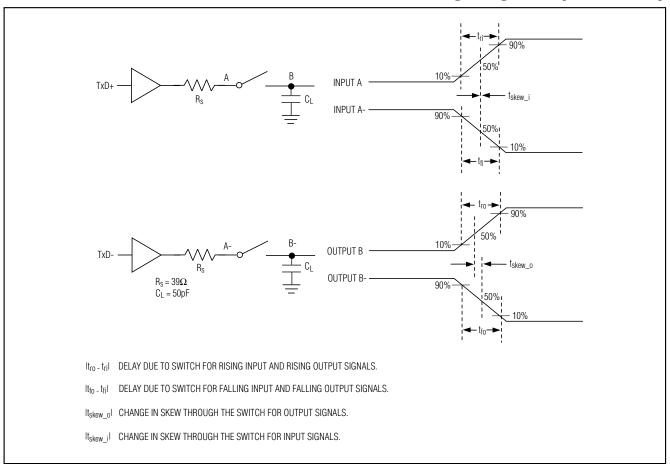


Figure 3. Input/Output Skew Timing Diagram

## Test Circuits/Timing Diagrams (continued)

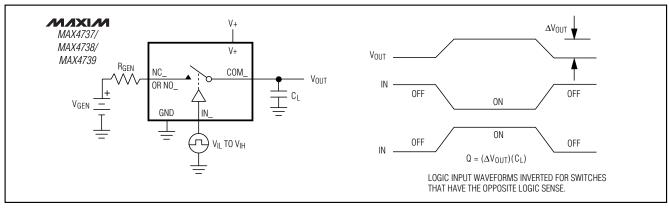
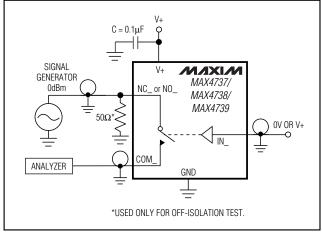


Figure 4. Charge Injection



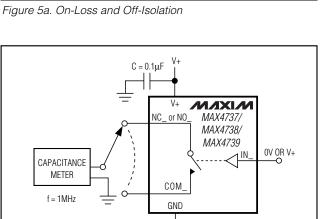


Figure 6. Channel Off/On-Capacitance

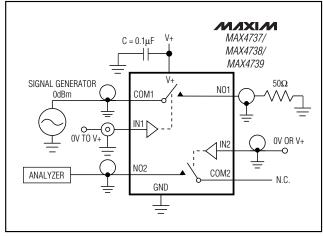


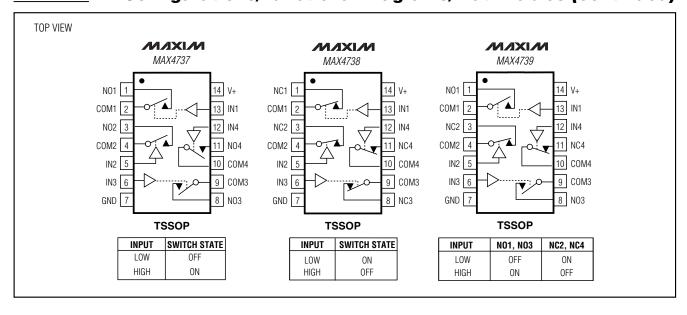
Figure 5b. Crosstalk Test Circuit

## Chip Information

TRANSISTOR COUNT: 361

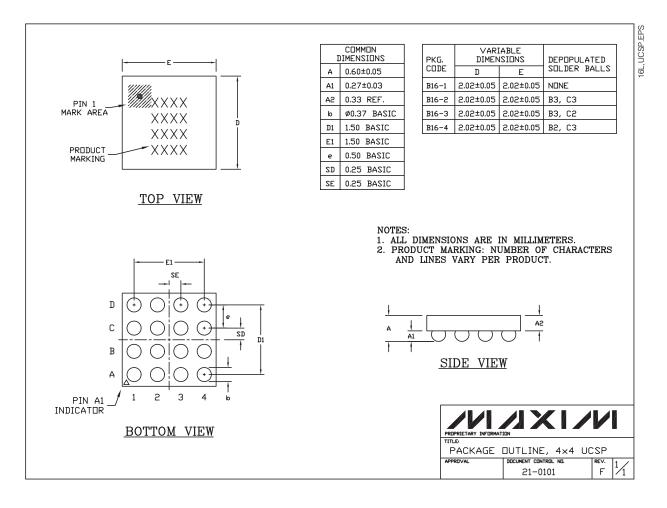
PROCESS: CMOS

### Pin Configurations/Functional Diagrams/Truth Tables (continued)



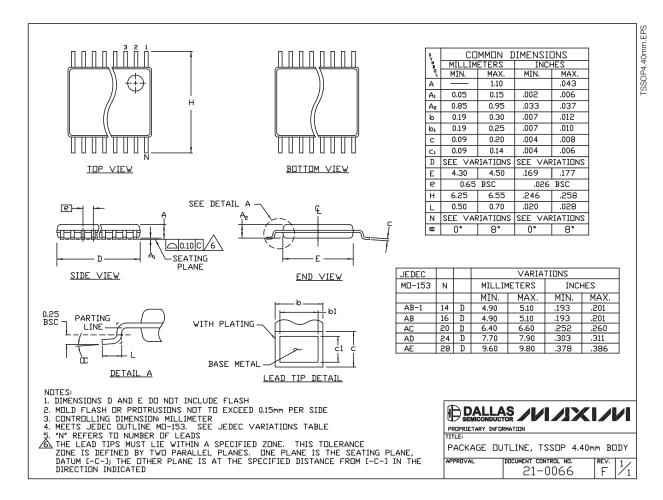
#### **Package Information**

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



#### Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



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